

KISM 2025 BUSAN

Re:Innovation of Semiconductor Manufacturing for AI Ecosystem

[WeF3] Advanced Designs, Processing, and Re

Session Date November 12 (Wed.), 2025

Session Time 16:05-17:45

Session Room F (Panorama Room, 16F)

[WeF3-1] [Invited] 16:05-16:25

Advanced Flip-Chip Bonding Process via Intense Pulsed Light Irradiation: From Single-Chip to Multi-Chip Stacking Applications

Young-Min Ju, Jong-Whi Park, Hyeong-bin Park, Yun-Joong Kim, and Hak-Sung Kim (Hanyang Univ., Korea)

[WeF3-2] [Invited] 16:25-16:45

Statistical Signal Integrity Analysis with Nonideal Buffer of DFE for Chiplet

Junyong Park (Kyung Hee Univ., Korea)

[WeF3-3] [Invited] 16:45-17:05

Visualized Thermo-Mechanical Failure Mechanisms in Advanced Semiconductor Package Interconnects via Microscale Deformation Analysis

Tae-Ik Lee (KITECH, Korea)

[WeF3-4] 17:05-17:25

3D-Printed Organic Interposer with Embedded Fan-Out Interconnects Enabled by Additive Manufacturing

Haksoon Jung and Jimin Kwon (UNIST, Korea)

[WeF3-5] 17:25-17:45

Predictive Analysis of Signal Transmission in Pogo Pin-Load Board

Jonghee Park and Youbean Kim (Myongji Univ., Korea)